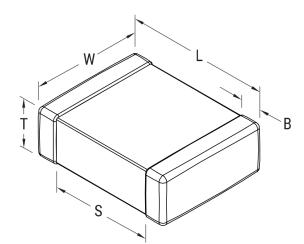


C0805C102J1GECTU

Aliases (C0805C102J1GEC7800)

ESD SMD Comm COG, Ceramic, 1000 pF, 5%, 100 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805



Click here for the 3D model.

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.9mm +/-0.10mm
S	0.75mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications Packaging

Packaging Packaging Quantity T&R, 180mm, Paper Tape 4000

General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	13 mg
Shelf Life	78 Weeks
MSL	1

Capacitance1000 pFMeasurement Condition1 MHz 1.0VrmsCapacitance Tolerance5%Voltage DC100 VDCESD Level per AEC-Q2008,000 V ESD LevelDielectric Withstanding Voltage250 VDCTemperature Range-55/+125°CTemperature CoefficientCOGCapacitance Change with Reference to30 ppm/C, 1MegaHz
Capacitance Tolerance5%Voltage DC100 VDCESD Level per AEC-Q2008,000 V ESD LevelDielectric Withstanding Voltage250 VDCTemperature Range-55/+125°CTemperature CoefficientCOGCapacitance Change with Reference to30 ppm/C, 1MegaHz
Voltage DC100 VDCESD Level per AEC-Q2008,000 V ESD LevelDielectric Withstanding Voltage250 VDCTemperature Range-55/+125°CTemperature CoefficientCOGCapacitance Change with Reference to30 ppm/C, 1MegaHz
ESD Level per AEC-Q2008,000 V ESD LevelDielectric Withstanding Voltage250 VDCTemperature Range-55/+125°CTemperature CoefficientCOGCapacitance Change with Reference to30 ppm/C, 1MegaHz
Dielectric Withstanding Voltage250 VDCTemperature Range-55/+125°CTemperature CoefficientC0GCapacitance Change with Reference to30 ppm/C, 1MegaHz
Temperature Range -55/+125°C Temperature Coefficient COG Capacitance Change with Reference to 30 ppm/C, 1MegaHz
Temperature Coefficient COG Capacitance Change with Reference to 30 ppm/C, 1MegaHz
Capacitance Change with Reference to 30 ppm/C, 1MegaHz
+25°C and 0 VDC Applied (TCC) 1.0Vrms
Dissipation Factor 0.1% 1 MHz 1.0Vrms
Aging Rate 0% Loss/Decade Hour
Insulation Resistance 100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

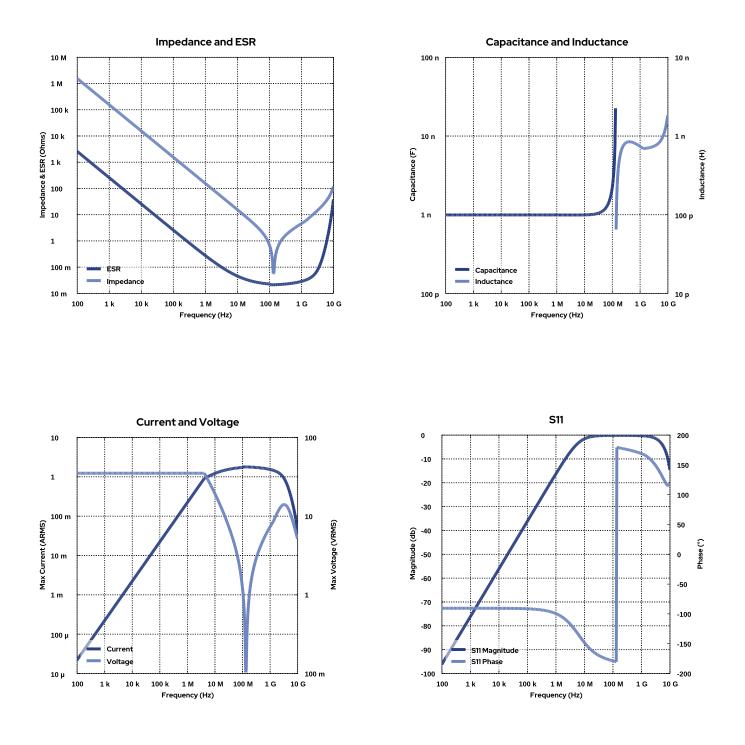


CO805C102J1GECTU Aliases (C0805C102J1GEC7800)

ESD SMD Comm COG, Ceramic, 1000 pF, 5%, 100 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805

Simulations

For the complete simulation environment please visit K-SIM.

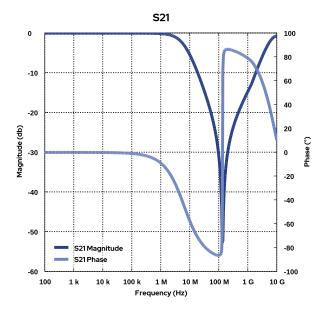






Aliases (C0805C102J1GEC7800)

ESD SMD Comm COG, Ceramic, 1000 pF, 5%, 100 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805





C0805C102J1GECTU

Aliases (C0805C102J1GEC7800)

ESD SMD Comm COG, Ceramic, 1000 pF, 5%, 100 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance. The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other
- harmonics
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.